

HIGHLIGHT

Fully-Automatic
Non-Contact
BG Tape Peeler

RAD-3020F/12



 Non-contact BG tape peeling

 Non-contact wafer handling

 Unique peeling method

 Ideal for TAIKO® and MEMS



LINTEC Corporation

BENEFITS



Non-contact BG tape peeling

LINTEC's non-contact vacuum wafer table securely holds the wafer during peeling, touching it only on the edge-exclusion area.



Non-contact wafer handling

Prevents contact with sensitive surfaces or metalizations and is ideally suited for TAIKO® or MEMS wafers.



Warpage-correction unit

Optionally, this feature supports handling of thin and warped wafers.



Unique peeling method

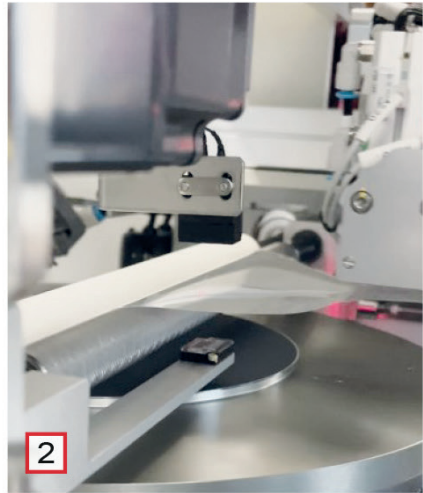
Minimizes wafer stress and even enables non-contact peeling of ultra-thin wafers and TAIKO® membranes.



PEELING PROCESS



Heat seal tape attachment

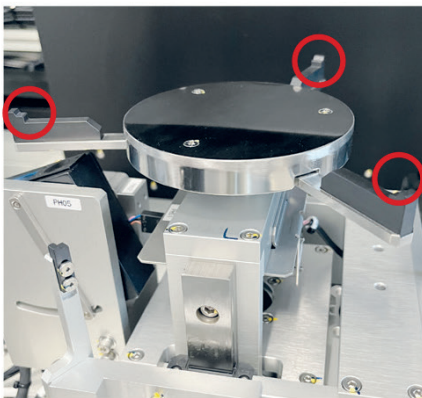


BG tape peeling

A heat-seal peeling-tape is thermocompression-bonded to the BG tape within 3mm of the wafer's periphery and then peeled from the wafer in an ideal 180 degree angle.

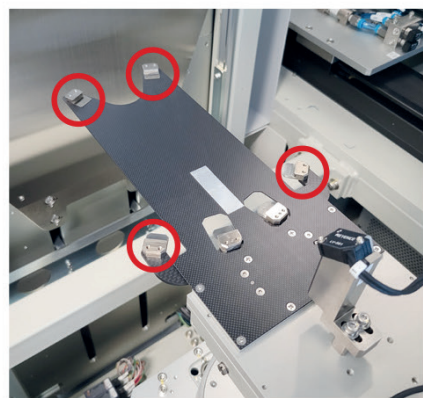
LINTEC's unique peeling method minimizes stress to the wafer and prevents wafer lift-off caused by a vacuum leak.

NON-CONTACT WAFER HANDLING I



Non-contact alignment

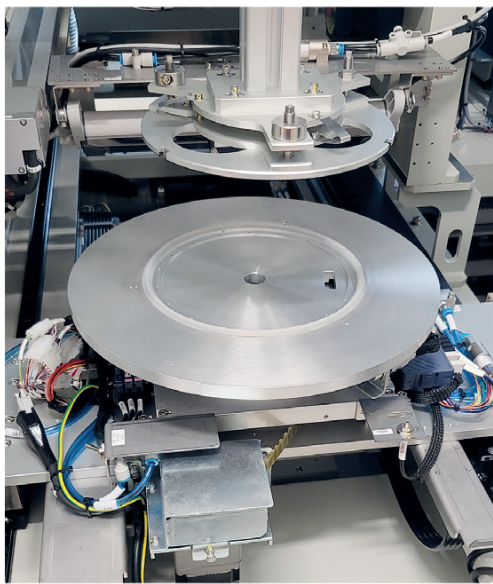
Precise positioning, touching the wafer on only 3 points on the wafer-edge



Non-contact handling

Prevents damage to sensitive wafer front- or backsides

NON-CONTACT WAFER HANDLING II



Using a unique non-contact vacuum wafer-table, wafers are securely held in place on the edge-exclusion area only.

This approach makes RAD-3020F/12 ideally suited for TAIKO®-wafers, MEMS and Power-Devices.

SPECIFICATION

Weight	1,600kg
Wafer size	300mm, 200mm Optional: 150mm
Wafer cassette	ø300mm: FOSB, FOUP (Index pitch = 10mm) ø200mm: Open cassette (Index pitch = 6.35mm)
Peeling tape	Heat seal tape
UPH	45 wafers/hour* *UPH measured under the condition of standard spec and Ø200mm full thickness wafer.



STANDARD

- Non-contact wafer edge-clamp handling system
- Non-contact vacuum wafer-table
- Non-contact wafer aligner
- Built-in UV-irradiation unit
- Single load port for FOUP/FOSB or cassette
- Anti-ESD specification:
±100V or less within 10sec after the end of operation



OPTIONS

- Handling of 150mm wafers
- Warped wafer handling specification
- Multi-functional handy barcode-reader
- Host Communication function (SECS/GEM)
- OHT capability
- ULPA filter clean-air spec



Adwill

Tape x Equipment

Contact us.
We look forward
to meeting you!



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